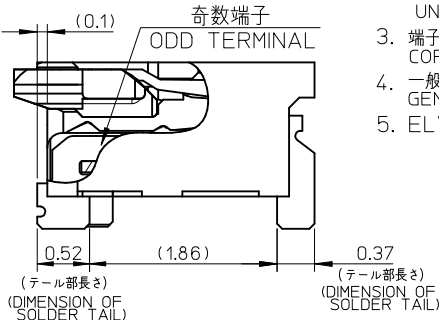
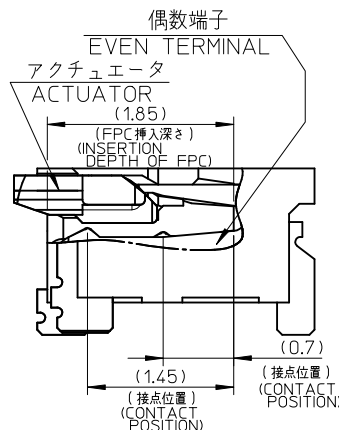


アクチュエータ開放位置
ACTUATOR OPENING POSITION

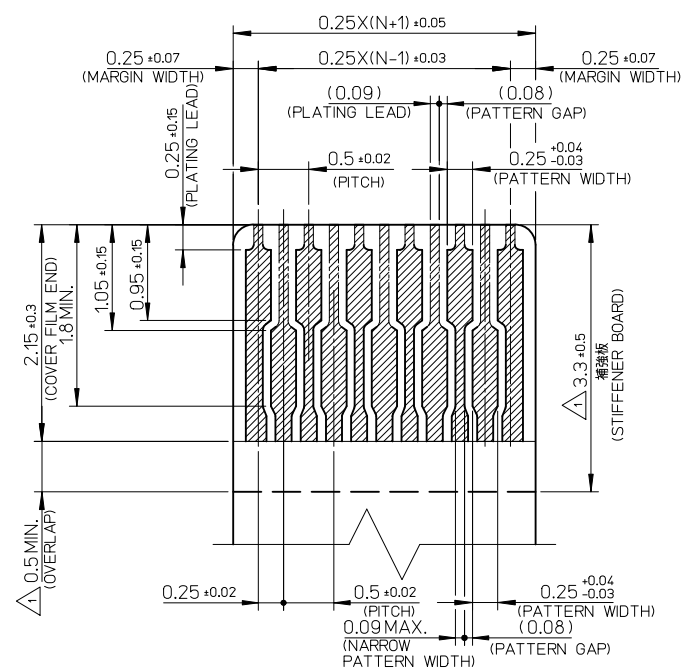
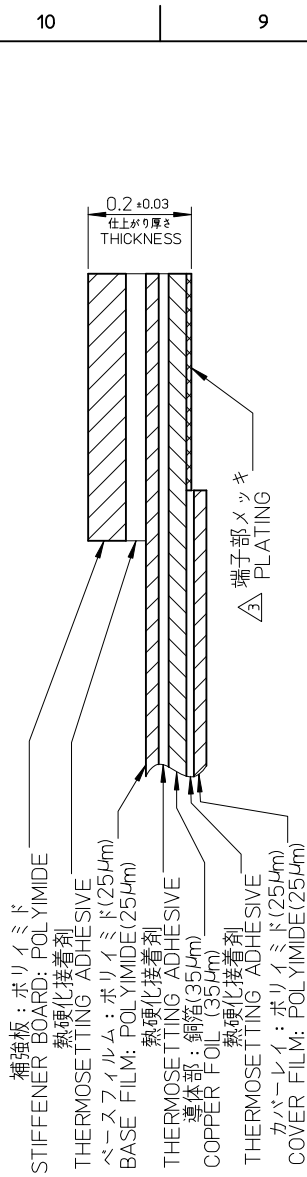


注記 NOTES

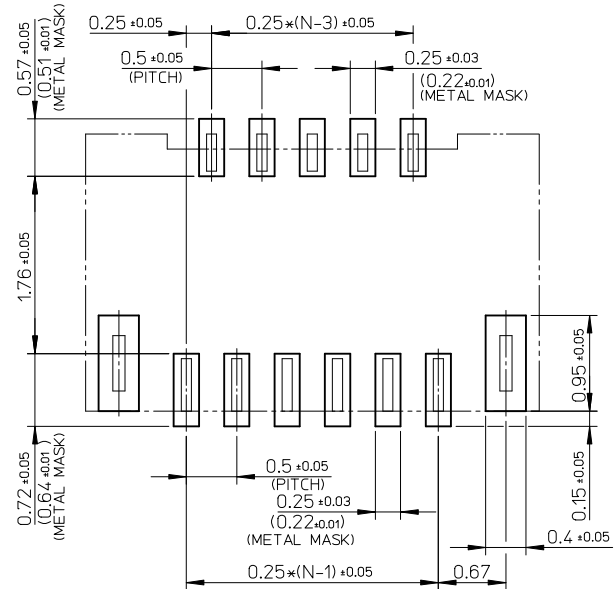
1. 使用材料 MATERIALS
 ハウジング : 液晶ポリマー(ガラス充填, UL94V-0, ベージュ)
 アクチュエータ : ポリアミド(ガラス充填, UL94V-0, 黒色)
 奇数端子 : 銅合金
 偶数端子 : 銅合金
 補強金具 : 銅合金
 HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED, BEIGE)
 ACTUATOR : POLYAMIDE (GLASS FILLED, BLACK)
 ODD TERMINAL : COPPER ALLOY
 EVEN TERMINAL : COPPER ALLOY
 FITTING NAIL : COPPER ALLOY
2. メッキ仕様 PLATING
 端子 TERMINAL
 テール部 : 部分金メッキ
 接点部 : 部分金メッキ 0.1μm MIN.
 下地 : ニッケルメッキ 1.0μm MIN.
 TAIL AREA : SEPARATED GOLD PLATING
 CONTACT AREA : SEPARATED GOLD PLATING 0.1μm MIN.
 UNDER PLATING : NICKEL PLATING 1.0μm MIN.
 金具 FITTING NAIL
 テール部 : スズメッキ 0.5μm MIN.
 下地 : ニッケルメッキ 1.0μm MIN.
 TAIL AREA : TIN PLATING 0.5μm MIN.
 UNDER PLATING : NICKEL PLATING 1.0μm MIN.
3. 端子、補強金具のコプラナリティーは 0.1 以下とする
 COPLANARITY OF SOLDER TAILS AND FITTING NAILS : 0.1MAX.
4. 一般公差 : ±0.3
 GENERAL TOLERANCES : ±0.3
5. ELV & RoHS COMPLIANT.

11.34	10.5	9.5	10.0	12.0	503320-4160	41
10.34	9.5	8.5	9.0	11.0	503320-3760	37
7.34	6.5	5.5	6.0	8.0	503320-2560	25
E	D	C	B	A	EMBOSSED PACKAGE	極数
CONNECTOR SERIES NO. 503320-**68						CIRCUITS
オオーダー番号 ORDER NO.						

REVISED EC NO: J2010-1518 DRWN: YFUJITA 2010/02/03 CHKD: SHOSHIKAWA 2010/02/04 APPR: SHOSHIKAWA 2010/02/04	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY M. TAKASAKI	DATE 2009/05/20	TITLE 0.25 PITCH FPC CONN E/O HGT=1.65 BTM CONTACT				
		10 OVER 30 UNDER	± ---	CHECKED BY M. HAYASHI	DATE 2009/05/20	MOLEX INCORPORATED				
		30 OVER	± ---	APPROVED BY N. UKITA	DATE 2009/05/20	DOCUMENT NO. SD-503320-001				
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2				
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



適合するFPC 推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(端子部仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)



FPC 挿入側
FPC INSERTION SIDE
参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS (REF.)

注記 NOTES

- 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を 0.5mm 以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT BE SECURED AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM
- 推奨マスク厚 : 100µm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100µm
RECOMMEND SCREEN OPEN RATIO : 80%

- FPCパターンのメッキ仕様は
金メッキ : 0.1µm以上
下地ニッケルメッキ : 2~6µm
FPC PATTERN PLATING
GOLD PLATING : 0.1µm MINIMUM
NICKEL UNDER PLATING : 2~6µm

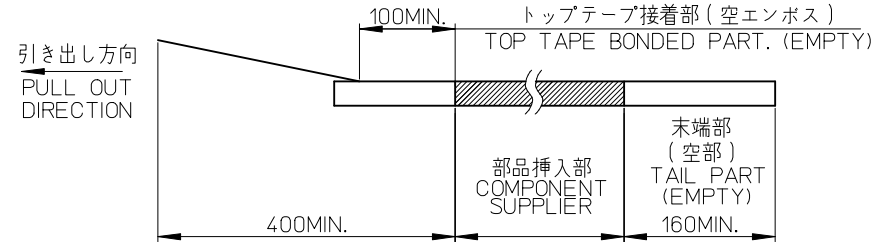
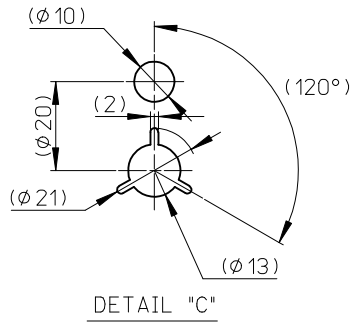
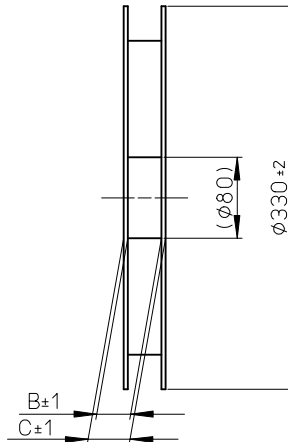
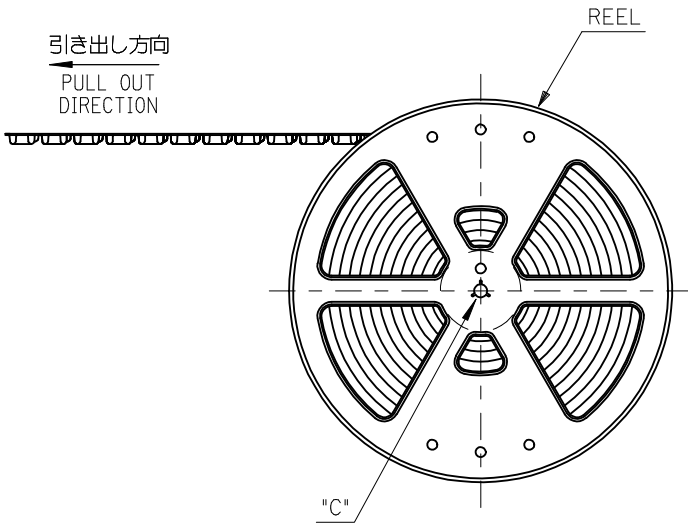
4 FPCについて (ABOUT FPC)
抜き方向は、導体側から補強板側を推奨します
補強板材質は、ポリイミドを推奨します
接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しがないよう、お願いします
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY

REVISED EC NO.: J2010-1518 DRWN: YFUJITA 2010/02/03 CHKD: SHOSHIKAWA 2010/02/04 APPR: SHOSHIKAWA 2010/02/04	DESCRIPTION 10 UNDER 10 OVER 30 UNDER 30 OVER ANGULAR ±1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER ± ---	DRAWN BY M. TAKASAKI	DATE 2009/05/20	TITLE 0.25 PITCH FPC CONN E/O HGT=1.65 BTM CONTACT	
		10 OVER 30 UNDER ± ---	CHECKED BY M. HAYASHI	DATE 2009/05/20	MOLEX MOLEX INCORPORATED	
		30 OVER ± ---	APPROVED BY N. UKITA	DATE 2009/05/20		
A	REV	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-503320-001	SHEET NO. 2 OF 2		

注記 NOTES

- 製品詳細寸法については図面 SD-503320-001 を参照下さい。
RE DETAILED DIMENSION, SEE SD-503320-001
- 梱包数量: 3000 個/リール
NUMBER OF CONNECTORS: 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

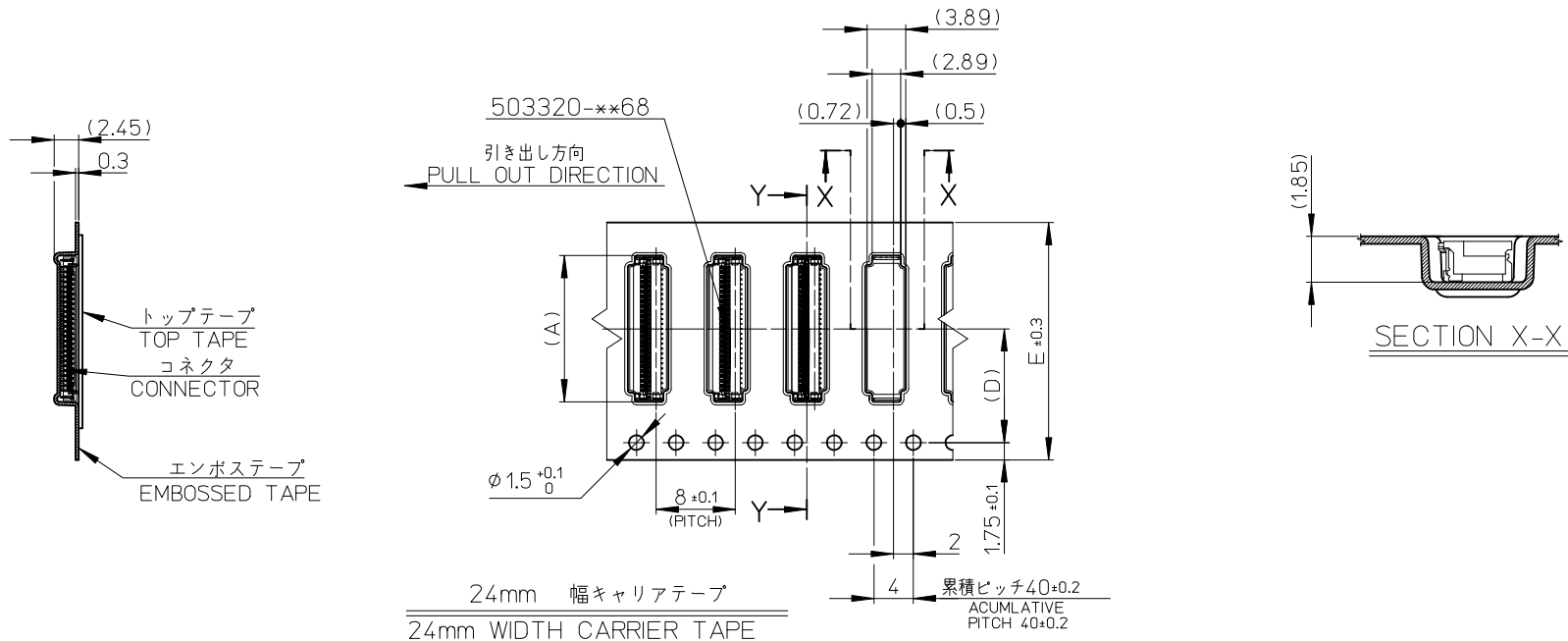
引き出し方向
PULL OUT
DIRECTION



- 材料 MATERIAL
 キャリアテープ (CARRIER TAPE): ポリスチレン (POLYSTYRENE)
 トップテープ (TOP TAPE): PET, PE, PEF
 リール (REEL): ポリスチレン (PS) <リサイクル材を含む>
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV & RoHS COMPLIANT

MATERIAL NO.	503320-**60
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION

RELEASED EC NO: J2010-0413 DRWN: CARIZONO 2009/09/15 CHKD: T. HARUYAMA 2009/09/15 APPR: NUKITA 2009/09/15	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC		TITLE 0.25MM PITCH FPC CONN HGT=1.65 HSG ASSY EMBOSSED TAPE PACKAGE MOLEX INCORPORATED	
	10 UNDER	± ---	DRAWN BY C. ARIZONO	DATE 2009/05/20	SHEET NO.		
	10 OVER 30 UNDER	± ---	CHECKED BY T. HARUYAMA	DATE 2009/05/20	1 OF 2		
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2009/05/20	DOCUMENT NO. SD-503320-002		
	ANGULAR ± --- °		MATERIAL NO.	SEE CHART			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



24	11.5	29.4	25.4	12.3	503320-4160	41
				11.3	503320-3760	37
				8.3	503320-2560	25
E キャリアテープ幅 CARRIER TAPE WIDTH	(D)	C	B	(A)	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CKT.
MATERIAL NO. 503320-**60						

RELEASED EC NO: J2010-0413 DRWN: C. ARIZONO 2009/09/15 CHKD: T. HARUYAMA 2009/09/15 APPR: N. UKITA 2009/09/15	DESCRIPTION REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY C. ARIZONO	DATE 2009/05/20	TITLE 0.25MM PITCH FPC CONN HGT=1.65 HSG ASSY EMBOSSED TAPE PACKAGE		
		10 OVER 30 UNDER	± ---	CHECKED BY T. HARUYAMA	DATE 2009/05/20	MOLEX INCORPORATED		
		30 OVER	± ---	APPROVED BY N. UKITA	DATE 2009/05/20	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-503320-002	SHEET NO. 2 OF 2
		ANGULAR ± --- °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								